MICROCHIP

Semiconductor Device Type: LT / LTY (8AX) 005 SC-70 NiPdAu

Termination Base Alloy: Copper Alloy (Cu)

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silica, vitreous	60676-86-0	Mold Compound	53.151	3.348	531,505
Epoxy Resin	Trade Secret	Mold Compound	3.830	0.241	38,300
Phenolic Resin	Trade Secret	Mold Compound	3.830	0.241	38,300
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.532	0.097	15,320
Carbon Black	1333-86-4	Mold Compound	0.188	0.012	1,876
Copper	7440-50-8	Lead Frame	24.821	1.564	248,212
Iron	7439-89-6	Lead Frame	0.587	0.037	5,867
Phosphorous	7723-14-0	Lead Frame	0.064	0.004	638
Zinc (Metal)	7440-66-0	Lead Frame	0.038	0.002	383
Aluminum oxide	1344-28-1	Die Attach	0.601	0.038	6,012
Diethylene glycol monoethyl ether acetate	112-15-2	Die Attach	0.601	0.038	6,012
Epoxy resin	Trade Secret - 10114	Die Attach	0.328	0.021	3,279
Epoxy resin	Trade Secret - 10105	Die Attach	0.164	0.010	1,640
Amine	Trade Secret - 10039	Die Attach	0.066	0.004	656
Silicon	7440-21-3	Chip (Die)	7.520	0.474	75,200
Gold	7440-57-5	Wire Bond	1.430	0.090	14,300
Nickel	7440-02-0	Plating on external leads (pins)	1.125	0.071	11,250
Palladium	5/3/7440	Plating on external leads (pins)	0.063	0.004	625
Gold	7440-57-5	Plating on external leads (pins)	0.063	0.004	625
		TOTALS:	**100.000**	**6.300**	**1,000,000**

0.0063 g Total Mass

Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)

JEDEC 97 Product Marking and/or Pkg. Labeling e4

3.94	(mg) Total	Mold Compound	% ot Total Weight	62.53
	Silica, vitreous	60676-86-0	85.00	
	Epoxy Resin	Trade Secret	6.13	
	Phenolic Resin	Trade Secret	6.13	
	Epoxy, Cresol Novolac	29690-82-2	2.45	
	Carbon Black	1333-86-4	0.30	
		Total	**100.00**	

1.61	(mg) Total	Lead Frame	% of Total Weight	25.51
	Copper	7440-50-8	97.30	
	Iron	7439-89-6	2.30	
	Phosphorous	7723-14-0	0.25	
	Zinc (Metal)	7440-66-0	0.15	
		Total	**100.00**	

0.11	(mg) Total	Die Attach	% of Total Weight	1.76
	Aluminum oxide	1344-28-1	34.16	
Diethylene glycol monoethyl ether acetate		112-15-2	34.16	
	Epoxy resin	Trade Secret - 10114	18.63	
	Epoxy resin	Trade Secret - 10105	9.32	
	Amine	Trade Secret - 10039	3.73	
		Total	**100.00**	

0.47	Total (mg)	Chip (Die)	% of Total Weight	7.52
	Doped Silicon	7440-21-3	100	
		Total	**100.00**	

0.09	(mg) Total	Wire Bond	% of Total Weight	1.43
	Doped Gold	7440-57-5	100	
		Total	**100.00**	

0.08	(mg) Total	Plating on external leads (pins)	% of Total Weight	1.25
	Nickel	7440-02-0	90.00	
	Palladium	7440-05-3	5.00	
	Gold	7440-57-5	5.00	
		Total	**100.00**	

6.300				100.000

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table